

Title (en)  
Floor System

Title (de)  
Bodensystem

Title (fr)  
Système de plancher

Publication  
**EP 1790795 A1 20070530 (EN)**

Application  
**EP 05111384 A 20051128**

Priority  
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Abstract (en)  
The present invention discloses a floor system comprising coupling means (1) for coupling of at least two floor plates (2,2') positioned side by side forming a joint (3) between the floor plates. The floor plate (2) is provided with an engagable portion (4) with an undercut (5), wherein the coupling means (1) has an engaging portion (6) with an engaging part (7) which is dimensioned to, when mounted, extend into said undercut (5) of the engagable portion (4) of the edge side opposite the joint edge of the floor plate (2).

IPC 8 full level  
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Citation (search report)

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